

Intel Technology and Product Leadership

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A Series of Firsts...

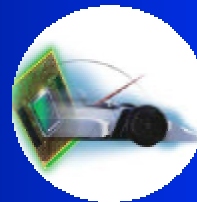
First in Every Mobile PC Segment



First in Bringing Mobile Technologies To The Market



Low Power



High Performance

First on Next Generation Process

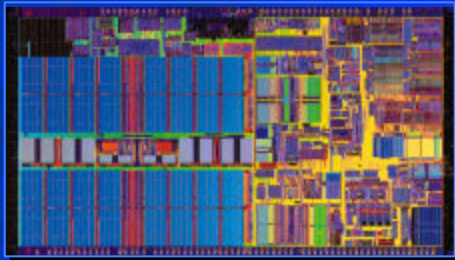
0.13 Micron Microprocessor in Nov '00

0.13 Micron Production in Q1 '01

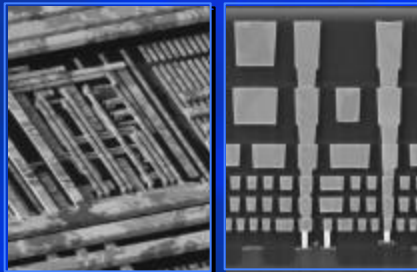
0.13 Micron Circuit on 300mm Wafer in Mar '01



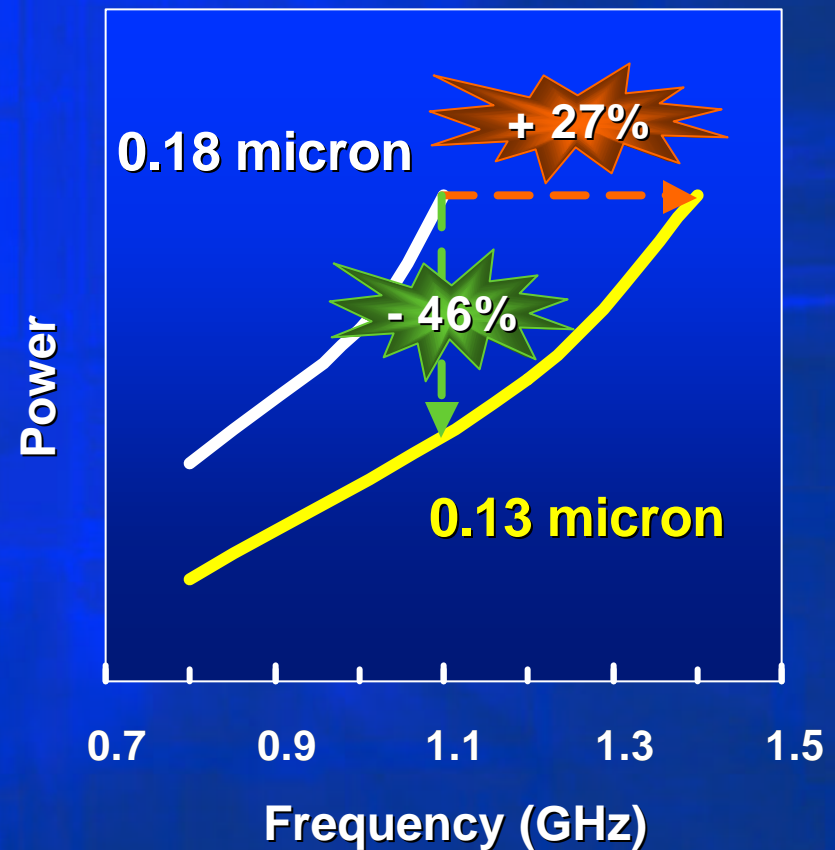
Designed For High Performance at Low Power



Fastest & Lowest Power
Transistors



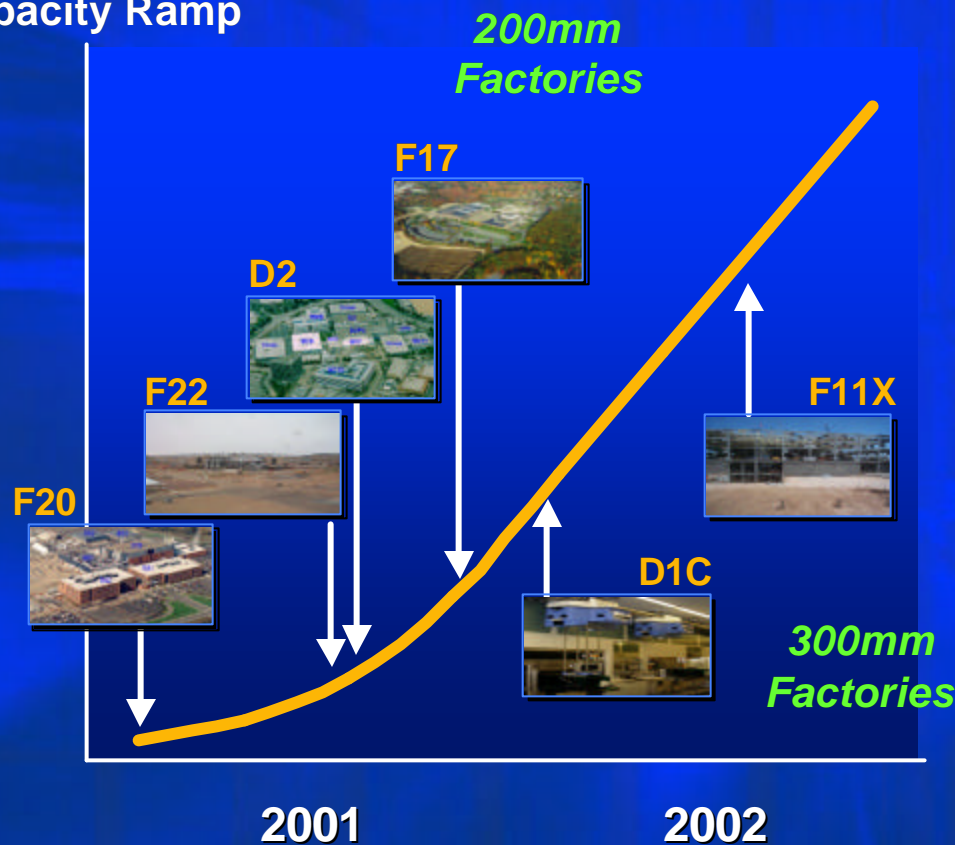
High Performance
Copper Interconnects



Flexibility to Deliver Higher Performance or Lower Power

Available in Volume Now

0.13 Micron
Capacity Ramp



✍ Six factories
readying 0.13
micron production

- Plans to spend \$7.5B on capital in 2001

✍ Yields and Volume
Exceeding
Expectations

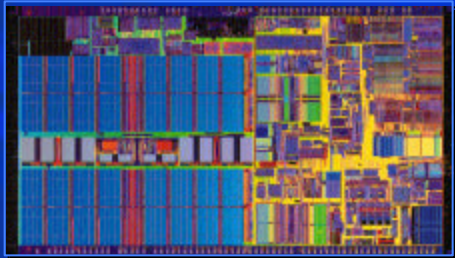
- 0.13 micron products have been shipping since May



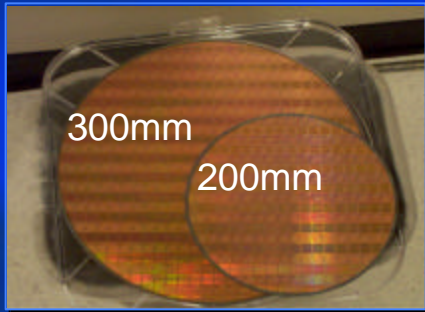
Intel's Fastest Process Technology Ramp Ever

Ideal Across Multiple Segments

Intel 0.13 Micron
Technology

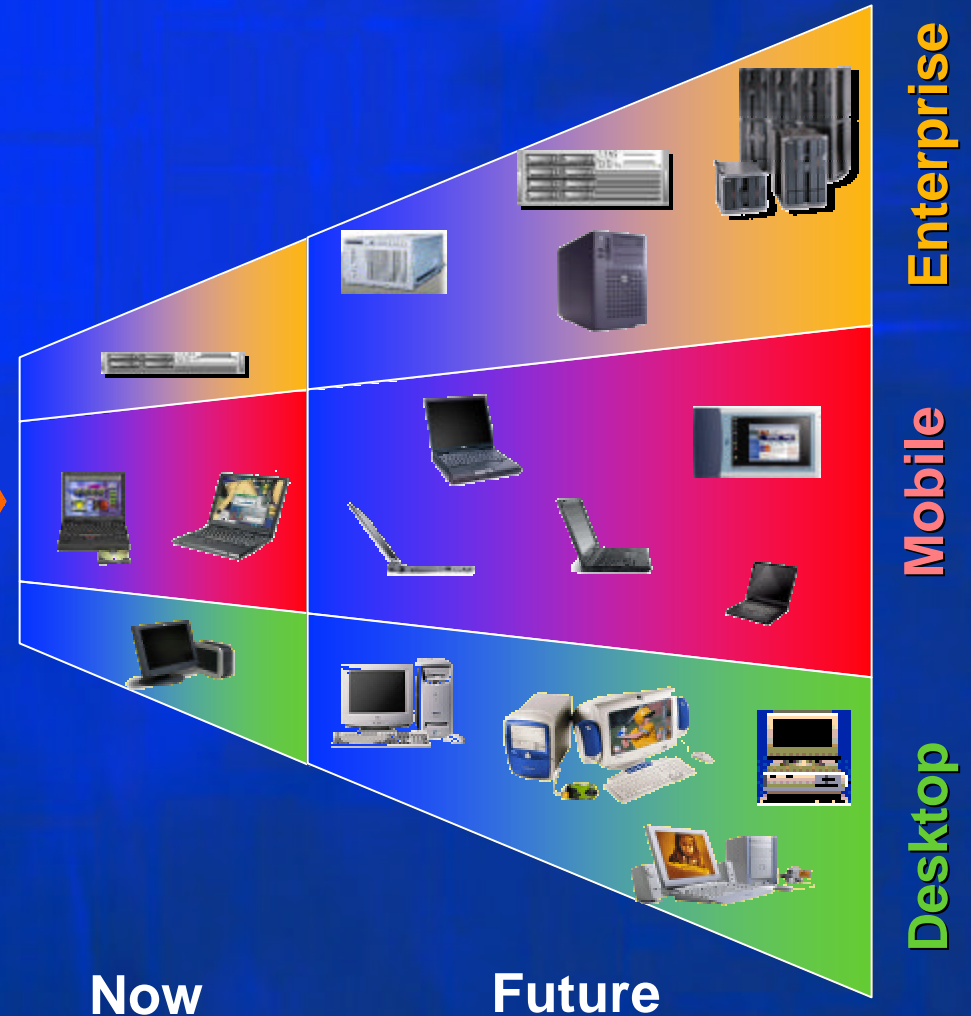
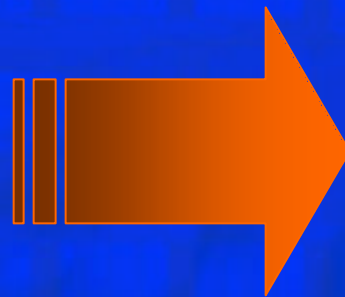


Fastest & Lowest Power
Transistors



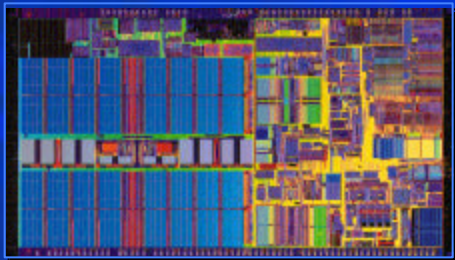
High Volume

intel®

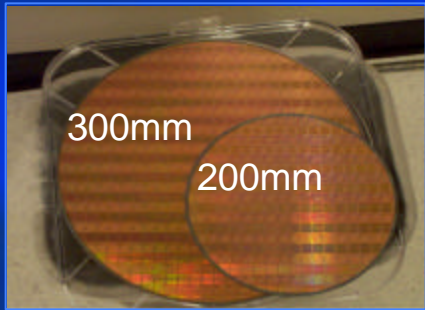


Pervasive Across Multiple Brands

Intel 0.13 Micron
Technology

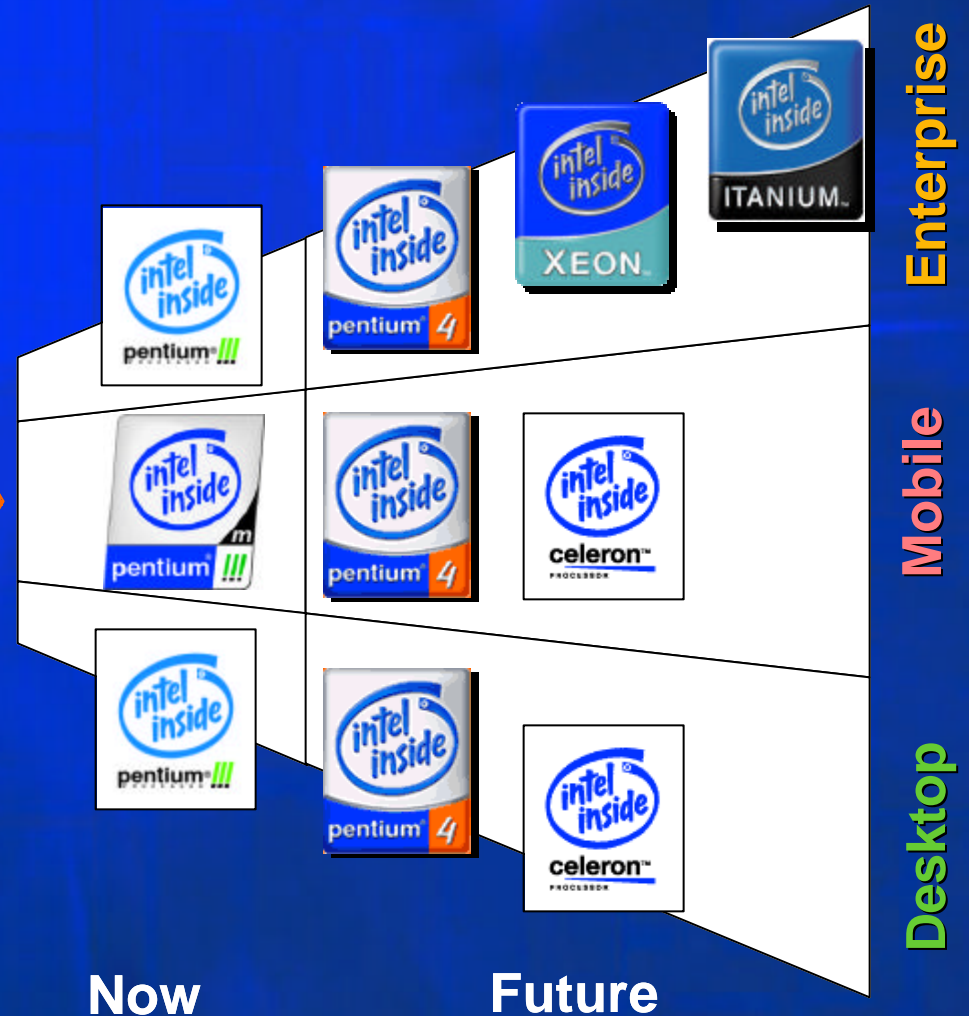
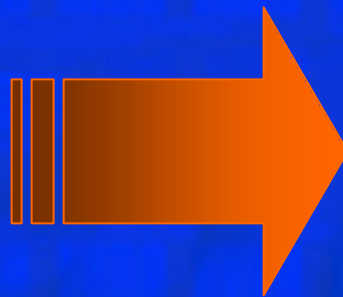


Fastest & Lowest Power
Transistors



High Volume

intel®



In Summary...

Intel leading transition to 0.13 micron process

- High performance at low power
- Available in volume now

Well suited to meet the needs of multiple segments

- Focus on Mobile PC segments today
- Will go across Desktop PC and Enterprise segments in the future